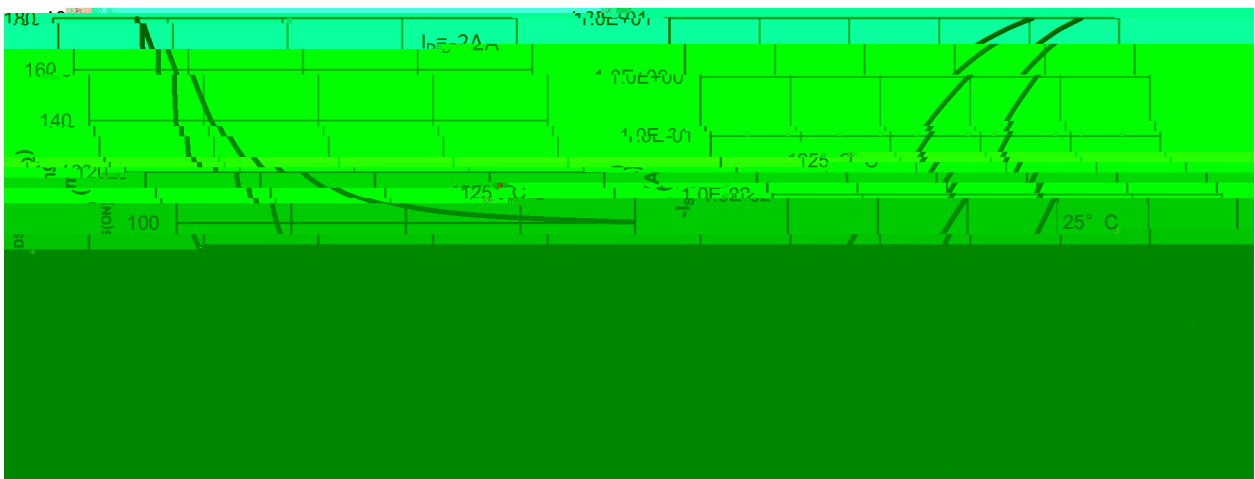
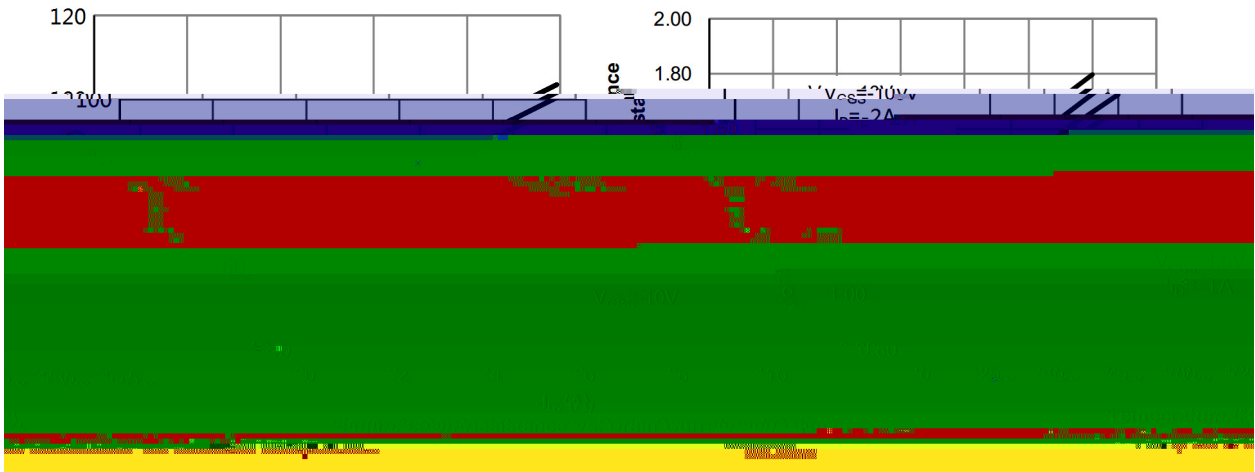
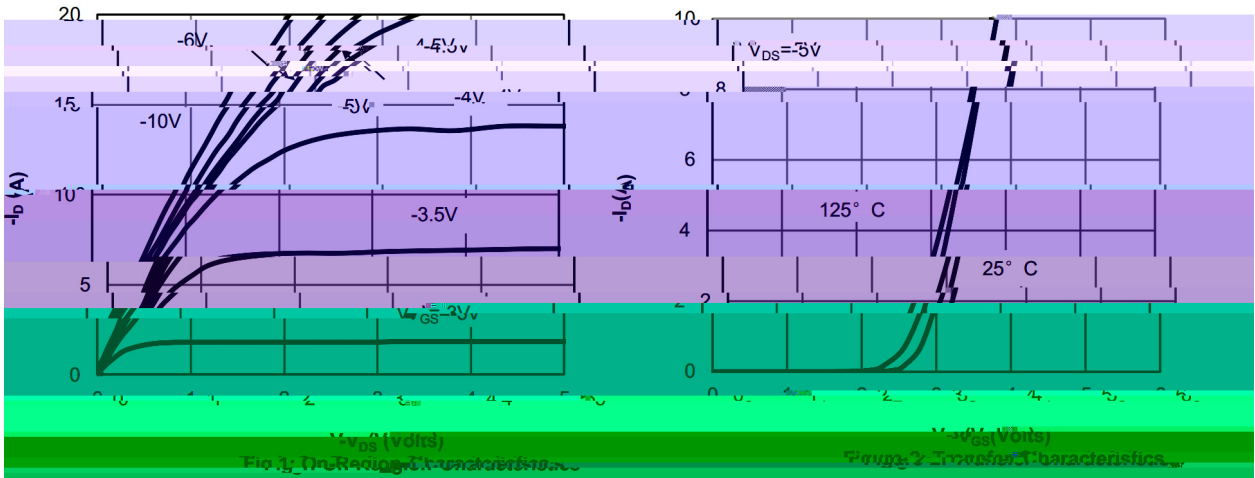
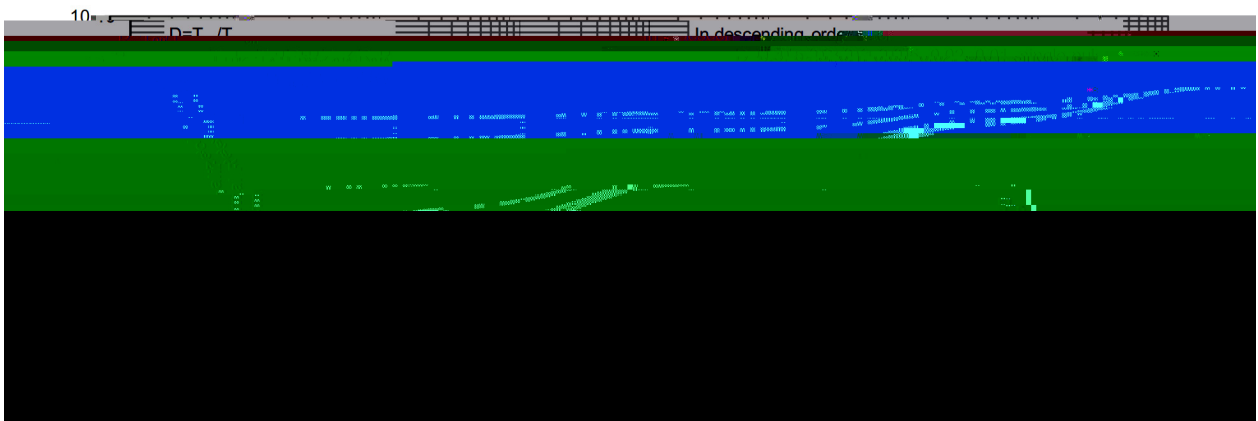
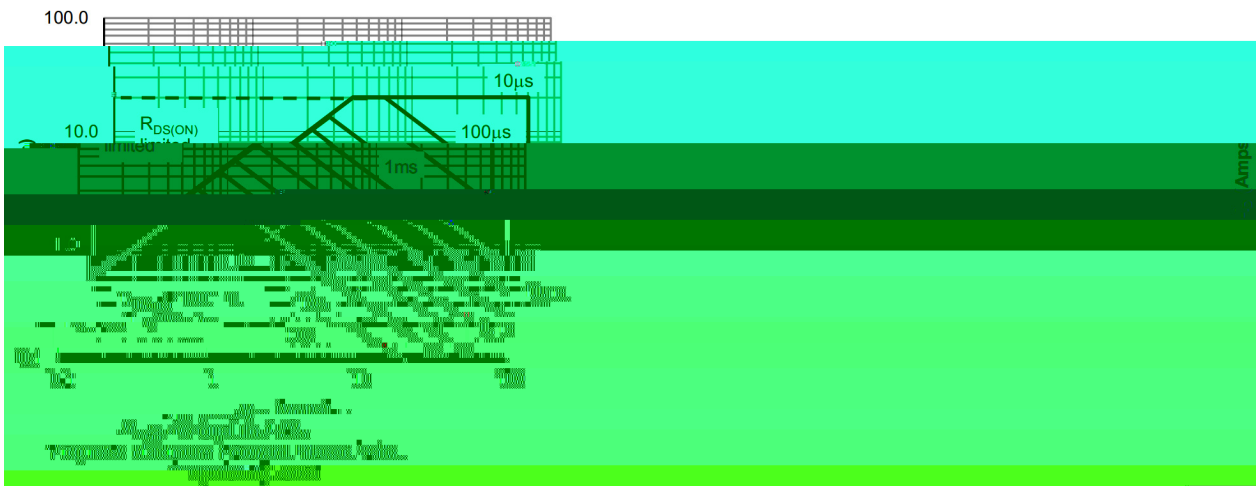
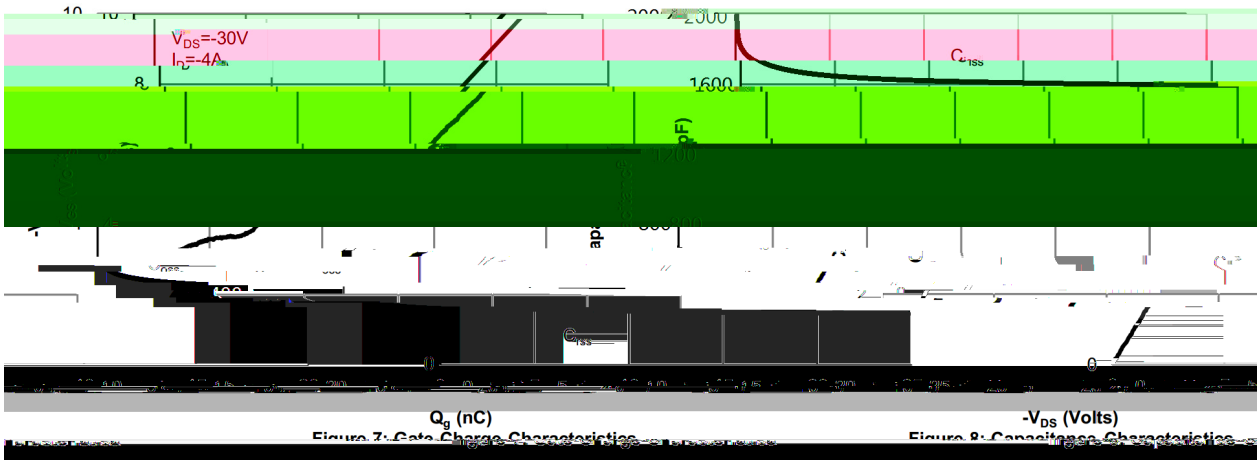




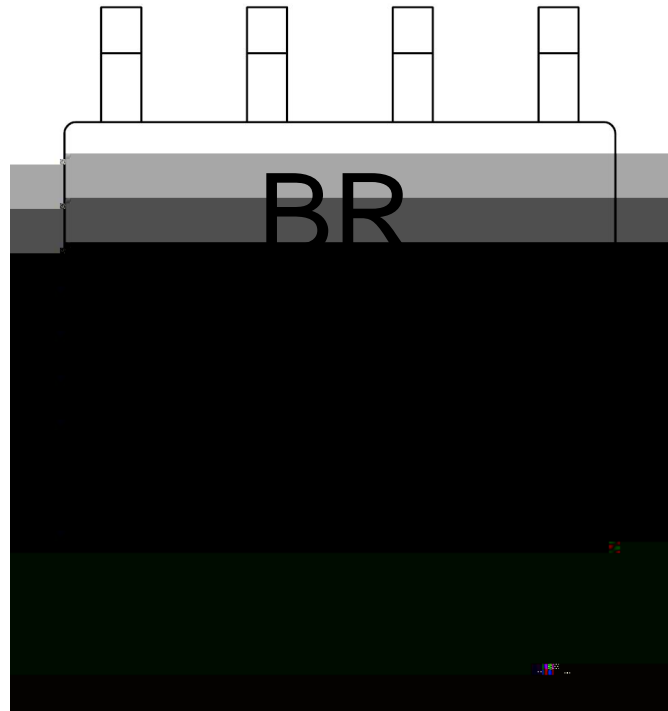
Parameter	Symbol	Rating	Unit	
Drain–Source Voltage	$V_{DSS}$	-60	V	
Gate–Body Leakage Voltage	$V_{GSS}$	$\pm 20$	V	
Drain Current - Continuous	$I_D$	-6	A	
Power Dissipation (Surface Mounted on FR4 Board, $t = 10$ sec.)	$P_D$	5.3	W	
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 150		
Maximum Junction-to-Ambient	$t = 10s$	$R_{JA}$	40	/W
Maximum Junction-to-Ambient	Steady-State		75	/W
Maximum Junction-to-Lead	Steady-State	$R_{JL}$	23.5	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V$ $I_D=-250$ A	-60	-71		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250$ A	-1	-2.1	-3	V
Static Drain–Source On–Resistance	$R_{DS(on)}$	$V_{GS}=-10V$ $I_D=-2A$		61	80	m
		$V_{GS}=-4.5V$ $I_D=-1A$		77	120	m
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-60V$ $V_{GS}=0V$			-1.0	A
Gate–Body Leakage.	$I_{GSS}$	$V_{GS}=-20V$			-100	nA
		$V_{GS}=20V$			100	nA
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V$ $I_S=-1A$ $T_J=25$				









BR

800P06

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Note:

BR: Company Code

800P06: Product Type

\*\*\*\*: Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)


Note:

1            150   180            60